

IN THE CLAIMS:

The status of each claim that has been introduced in the above-referenced application is identified in the ensuing listing of the claims. This listing of the claims replaces all previously submitted claims listings.

1. (Currently amended) A method for designing a rerouting element for use with a semiconductor device including at least one bond pad positioned substantially centrally on a surface thereof, comprising:

configuring at least one contact location adjacent to a first peripheral edge of ~~on~~ a first surface of a substantially planar member, the at least one contact location mirroring a position of the at least one bond pad on the surface of the semiconductor device;

configuring at least one conductive trace location extending from the at least one contact location toward a periphery of the substantially planar member; and

configuring at least one rerouted bond pad location proximate a second peripheral edge of the substantially planar member opposite the first peripheral edge of the substantially planar member, the periphery, the at least one rerouted bond pad location being configured to be exposed beyond a periphery of another semiconductor device upon positioning the another semiconductor device over the surface of the semiconductor device.

2. (Previously Presented) The method of claim 1, wherein configuring at least one contact location comprises configuring a plurality of contact locations, each contact location of the plurality of contact locations mirroring a location of a corresponding bond pad on the surface of the semiconductor device.

3. (Previously Presented) The method of claim 2, wherein configuring at least one conductive trace location comprises configuring a plurality of conductive trace locations, each conductive trace location of the plurality of conductive trace locations extending from a corresponding contact location toward the periphery of the substantially planar member.

4. (Previously Presented) The method of claim 3, comprising configuring each conductive trace location of the plurality of conductive trace locations to extend toward a single edge of the substantially planar member.

5. (Previously Presented) The method of claim 3, wherein configuring at least one rerouted bond pad location comprises configuring a plurality of rerouted bond pad locations, each rerouted bond pad location of the plurality of rerouted bond pad locations being continuous with an end of a corresponding conductive trace location and located proximate the periphery of the substantially planar member.

6. (Currently amended) The method of claim 5, comprising configuring each rerouted bond pad location of the plurality of rerouted bond pad locations is configured to be exposed beyond a periphery of the another semiconductor device upon positioning of the another semiconductor device over the surface of the semiconductor device.

7. (Currently amended) The method of claim 1, wherein configuring the at least one rerouted bond pad location comprises configuring the at least one rerouted bond pad location to facilitate connection of a discrete conductive element thereto with the another semiconductor device positioned over the surface of the semiconductor device.

8. (Currently amended) A method for assembling semiconductor devices in a stacked arrangement, comprising:
providing a first semiconductor device with at least one bond pad positioned substantially centrally on a surface thereof; and
positioning a first rerouting element over the surface of the first semiconductor device with a contact of the first rerouting element communicating with the at least one bond pad, a circuit trace of the first rerouting element extending laterally toward a periphery peripheral edge of the first semiconductor device and establishing communication between the at least one bond pad and at least one first rerouted bond pad located

~~proximate a periphery of the semiconductor device at a location where the at least one rerouted bond pad will remain exposed upon positioning another semiconductor device over the surface of the semiconductor device the first peripheral edge;~~

positioning a second semiconductor device having at least one bond pad positioned substantially centrally on a surface thereof over the first rerouting element with the first rerouted bond pad location being located adjacent to and exposed laterally beyond a peripheral edge of the second semiconductor device; and

positioning a second rerouting element over the surface of the second semiconductor device with a contact of the second rerouting element communicating with the at least one bond pad, a circuit trace of the second rerouting element extending laterally toward another peripheral edge of the second semiconductor device, located opposite the peripheral edge positioned adjacent to the first rerouted bond pad location, and establishing communication between the at least one bond pad and at least one second rerouted bond pad located proximate the another peripheral edge of the second semiconductor device.

9. (Previously Presented) The method of claim 8, wherein providing the semiconductor device comprises providing a semiconductor device with a plurality of bond pads, at least some of which are positioned at substantially central locations on the surface.

10. (Previously Presented) The method of claim 9, wherein positioning the rerouting element comprises positioning a rerouting element comprising:
a plurality of contacts, each contact of the plurality of contacts being positioned correspondingly to a position of a corresponding bond pad of the semiconductor device;
a plurality of conductive traces, each conductive trace of the plurality of conductive traces extending laterally from a corresponding contact of the plurality of contacts toward the periphery of the semiconductor device; and
a plurality of rerouted bond pads, each rerouted bond pad of the plurality of rerouted bond pads being positioned at an end of a corresponding conductive trace, proximate the periphery of the semiconductor device.

11. (Previously Presented) The method of claim 10, wherein positioning the rerouting element comprises positioning a rerouting element with each rerouted bond pad of the plurality of rerouted bond pads being positioned proximate a single peripheral edge of the semiconductor device.

12. (Previously Presented) The method of claim 10, wherein positioning the rerouting element comprises positioning a rerouting element with each rerouted bond pad of the plurality of rerouted bond pads being positioned to be exposed beyond a periphery of the another semiconductor device upon being positioned over the surface of the semiconductor device.

13. (Previously Presented) The method of claim 8, further comprising:
positioning the another semiconductor device over the rerouting element, the at least one rerouted bond pad of the rerouting element being exposed beyond a periphery of the another semiconductor device.

14. (Previously Presented) The method of claim 13, further comprising:
securing the semiconductor device to a carrier substrate.

15. (Previously Presented) The method of claim 14, wherein securing comprises
securing the semiconductor device to at least one of a circuit board, an interposer, an additional semiconductor device, and leads.

16. (Previously Presented) The method of claim 14, further comprising:
positioning at least one discrete conductive element between the at least one rerouted bond pad and a corresponding contact area of the carrier substrate.

17. (Previously Presented) The method of claim 16, wherein positioning comprises at least one of wire bonding, tape-automated bonding, and thermocompression bonding.

18. (Previously Presented) The method of claim 14, further comprising: encapsulating at least portions of the semiconductor device, the another semiconductor device, and regions of the carrier substrate adjacent to the semiconductor device.

19. (Previously Presented) The method of claim 18, wherein encapsulating comprises glob top encapsulating.

20. (Previously Presented) The method of claim 18, wherein encapsulating comprises one of transfer molding and pot molding.

21. (New) The method of claim 8, further comprising:
positioning a third semiconductor device having at least one bond pad positioned substantially centrally on a surface thereof over the second rerouting element with the second rerouted bond pad location being located adjacent to and exposed laterally beyond a peripheral edge of the third semiconductor device; and
positioning a third rerouting element over the surface of the third semiconductor device with a contact of the third rerouting element communicating with the at least one bond pad, a circuit trace of the third rerouting element extending laterally toward another peripheral edge of the third semiconductor device, located opposite the peripheral edge positioned adjacent to the second rerouted bond pad location, and establishing communication between the at least one bond pad and at least one third rerouted bond pad located proximate the another peripheral edge of the third semiconductor device.